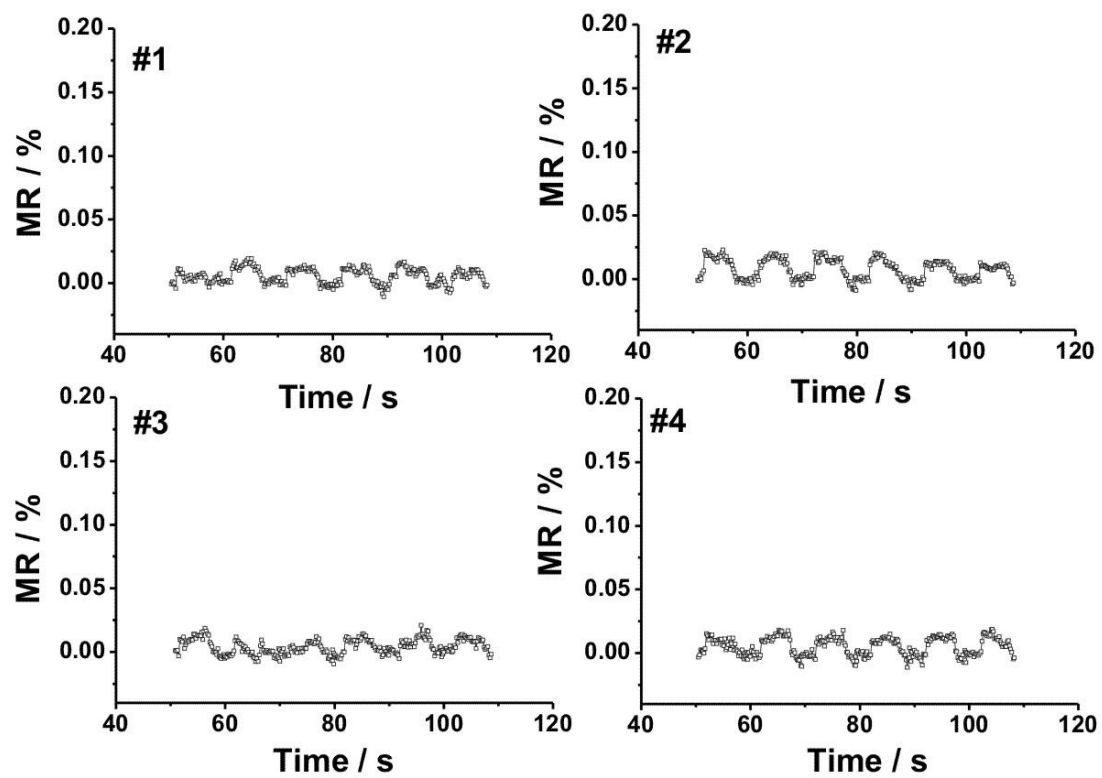


# Electronic Supplementary Information

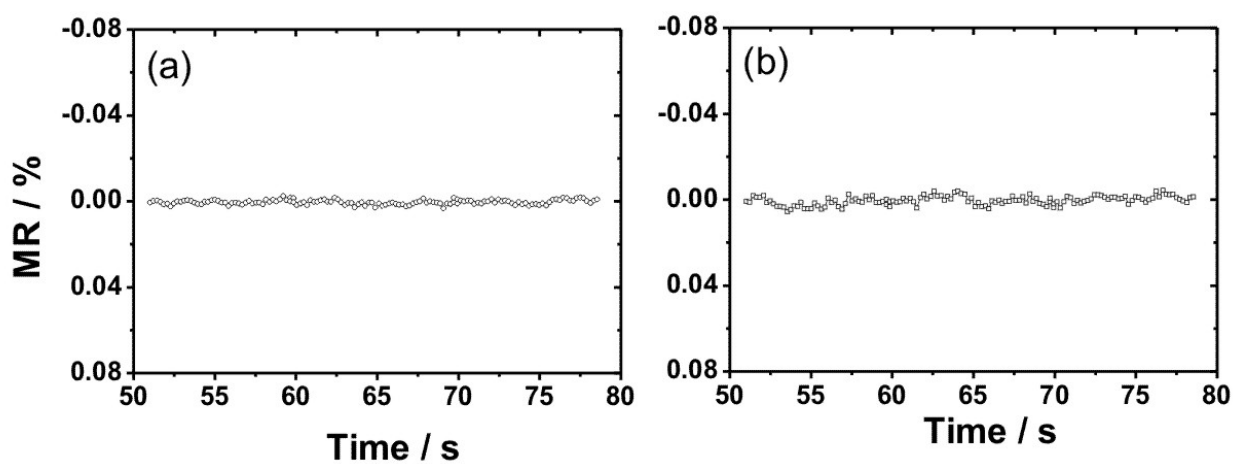
## **Revealing the origin of magnetoresistance in unipolar organic field-effect transistors**

By *Carolin Isenberg and Tobat P. I. Saragi\**

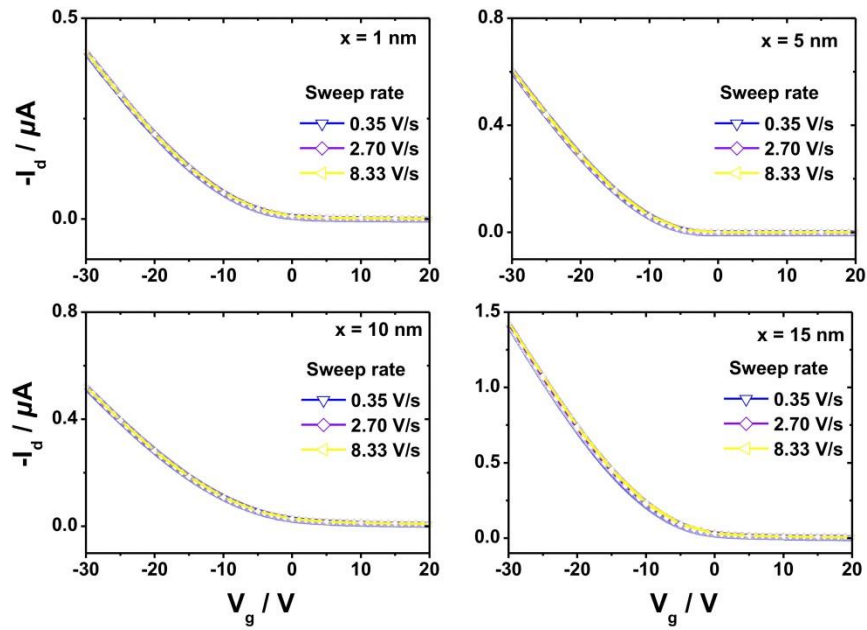
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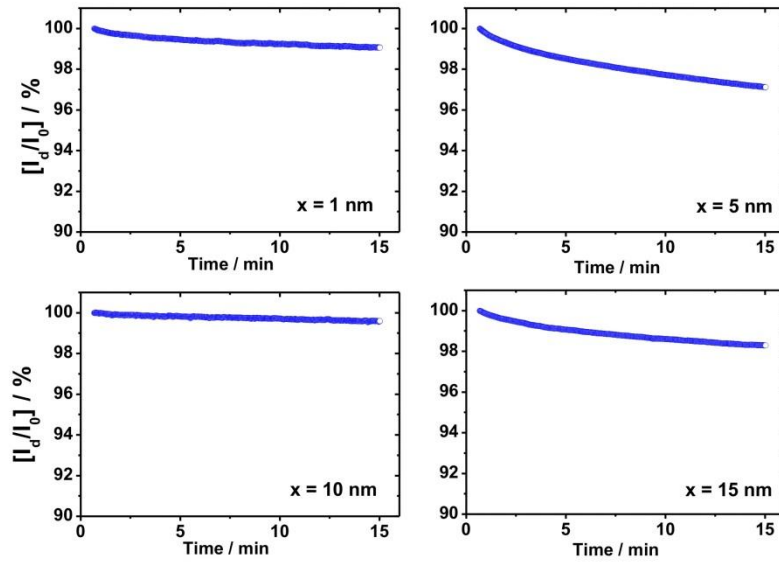
**Figure S1.** MR effects observed in four identical Spiro-TAD field-effect transistors (labeled as #1, #2, #3 and #4) fabricated on bare SiO<sub>2</sub> and measured at  $V_d = V_g = -40$  V under influence of a magnetic field of 96 mT and at room temperature.



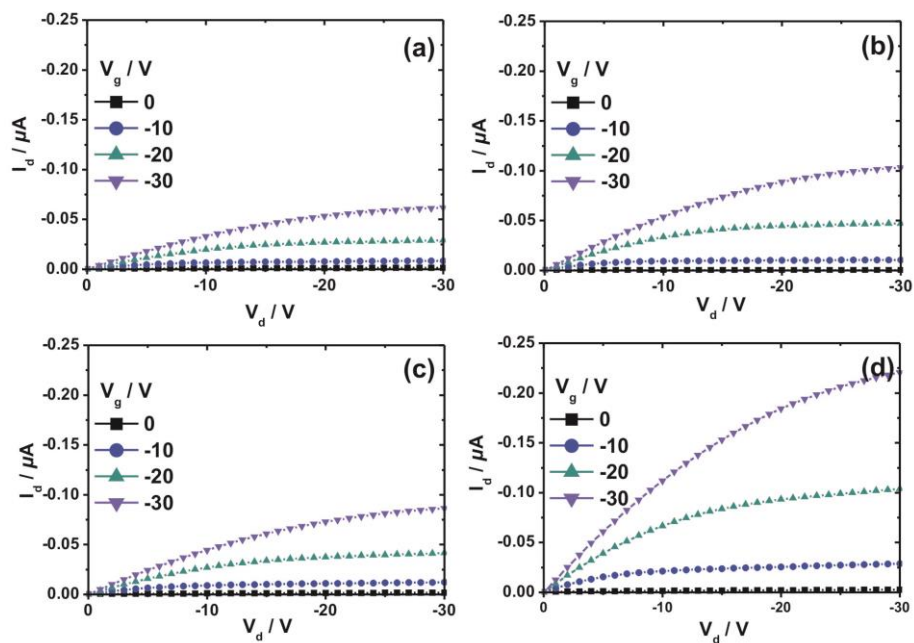
**Figure S2.** MR effects of a Spiro-TAD field-effect transistor fabricated on HMDS-treated SiO<sub>2</sub> gate dielectric and measured at (a)  $V_d = V_g = -80$  V and (b)  $V_d = V_g = -50$ , each at a magnetic field of 96 mT and at room temperature.



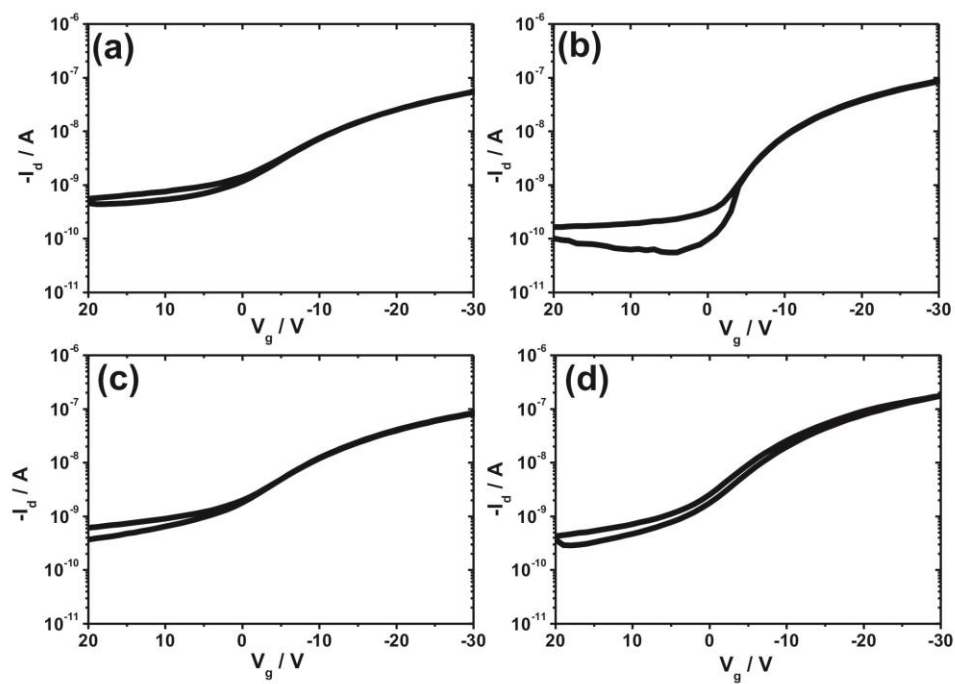
**Figure S3.** Transfer curves of F6-TNAP ( $x$  nm)/Spiro-TAD (40 nm) field-effect transistors fabricated on bare SiO<sub>2</sub> and recorded at different  $V_g$  sweep rate. Here,  $x$  is 1 nm, 5 nm, 10 nm and 15 nm, respectively.



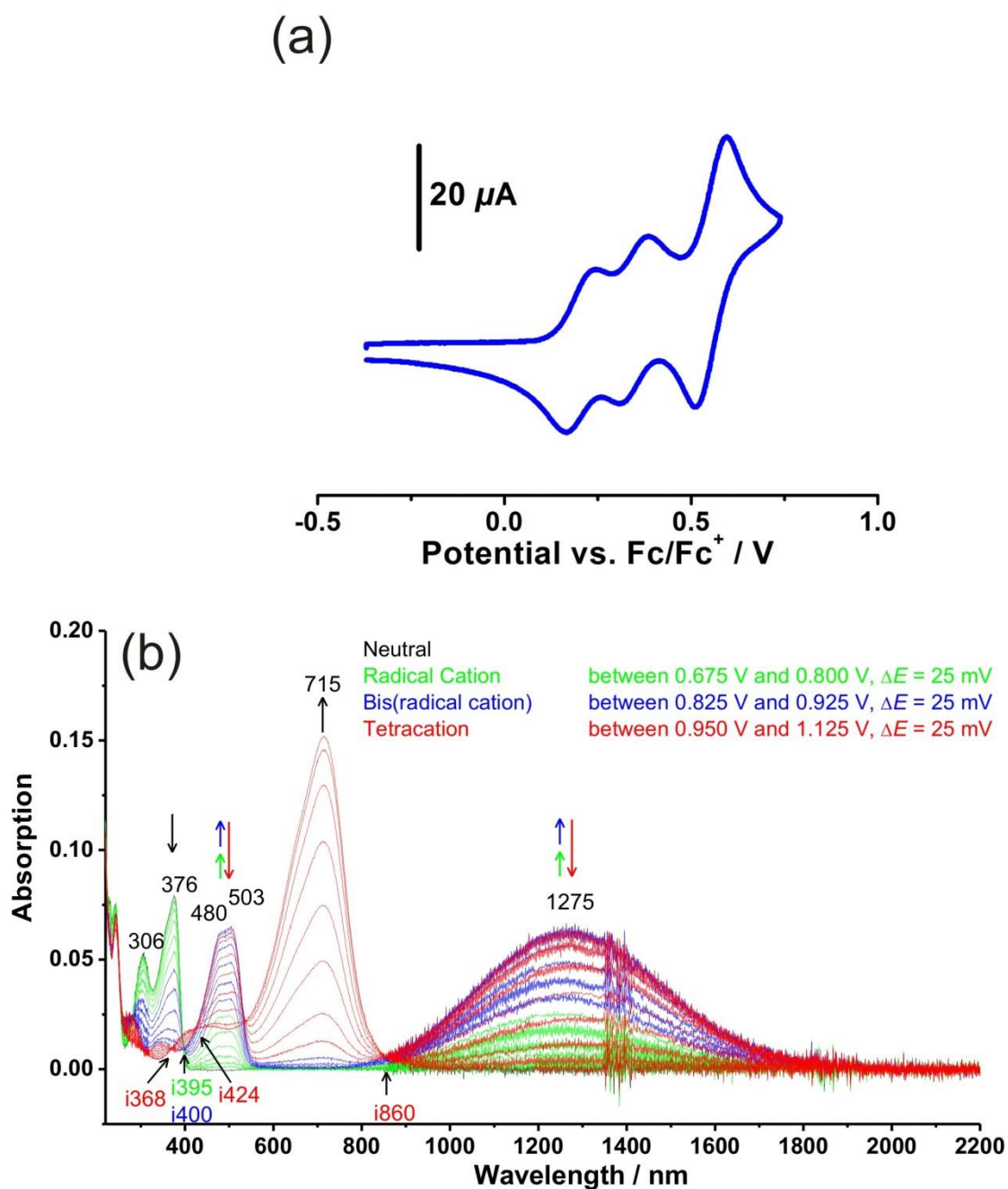
**Figure S4.** Bias stress effect of F6-TNAP ( $x$  nm)/Spiro-TAD (40 nm) field-effect transistors fabricated on bare SiO<sub>2</sub> and measured in the devices with different thickness of F6-TNAP. In this case,  $x$  is 1 nm, 5 nm, 10 nm and 15 nm, respectively. The relative drain current  $I_d/I_0$  was measured at  $V_d = V_g = -30$  V.



**Figure S5.** Output curves of F6-TNAP/Spiro-TAD (40 nm) field-effect transistor fabricated on bare SiO<sub>2</sub> and with different thickness of F6-TNAP. (a) F6-TNAP = 1 nm, (b) F6-TNAP = 5 nm, (c) F6-TNAP = 10 nm and (d) F6-TNAP = 15 nm.

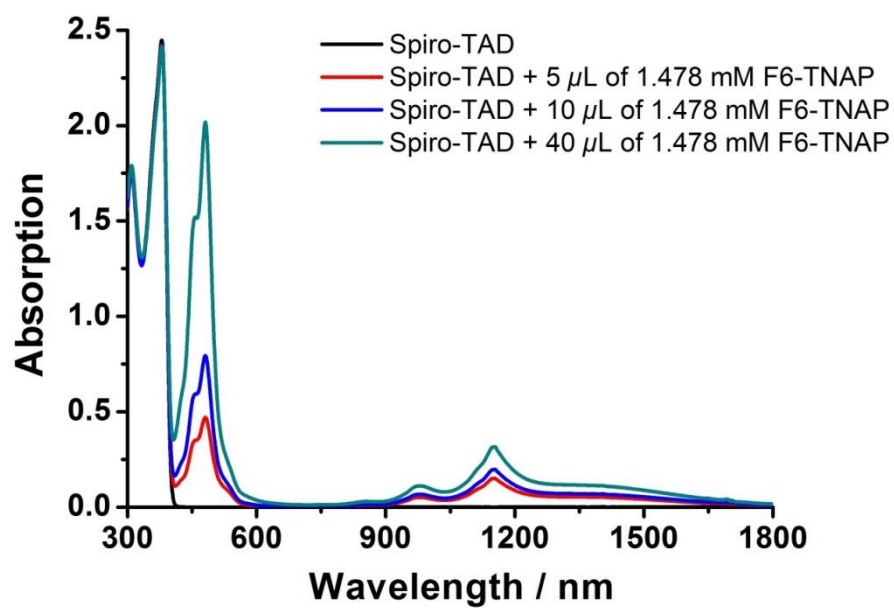


**Figure S6.** Transfer curves of F6-TNAP/Spiro-TAD (40 nm) field-effect transistor fabricated on bare SiO<sub>2</sub> and with different thickness of F6-TNAP. (a) F6-TNAP = 1 nm, (b) F6-TNAP = 5 nm, (c) F6-TNAP = 10 nm and (d) F6-TNAP = 1 nm.

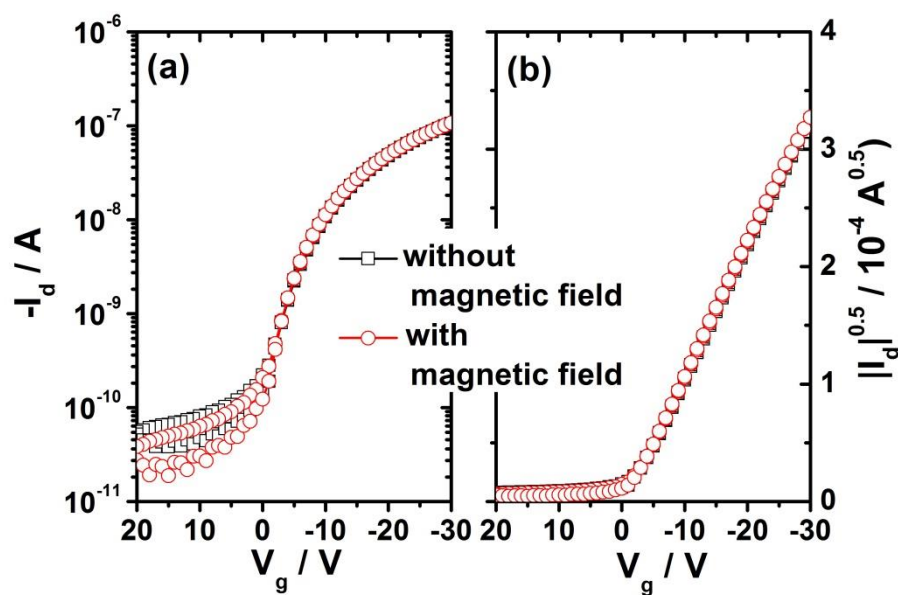


**Figure S7.** (a) Cyclic voltammogram of Spiro-TAD measured in  $\text{CH}_2\text{Cl}_2/0.1$  M TBAHFP. It exhibits half-wave potentials of the oxidation at  $-0.23$  V,  $-0.38$  V and  $-0.58$  V vs. ferrocene/ferrocenium ( $\text{Fc}/\text{Fc}^+$ ), respectively. (b) In-situ UV-Vis-NIR spectroelectrochemical measurement of Spiro-TAD in MeCN/ $0.1$  M TBAHFP at room temperature.





**Figure S8.** In-situ UV-Vis-NIR absorption spectra of Spiro-TAD (concentration 31  $\mu\text{M}$ ) measured in  $\text{CH}_2\text{Cl}_2$  and with additional concentration of organic molecular *p*-dopant F6-TNAP.



**Figure S9.** (a) Transfer characteristics and (b) square roots of absolute drain currents of a bilayer of F6-TNAP (5 nm)/Spiro-TAD (40 nm) field-effect transistor fabricated on bare SiO<sub>2</sub> measured at V<sub>d</sub> = -30 V, without and under a magnetic field of 96 mT.